MAY 1 2 2004 U

Docket No.: 50352-020 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277

Shiroshi MATSUKI, et al. : Confirmation Number: 9915

Serial No.: 09/944,344 : Group Art Unit: 1753

Filed: September 04, 2001 : Examiner: Edna Wong

For: MATERIAL FOR COPPER ELECTROPLATING, METHOD FOR MANUFACTURING SAME AND COPPER ELECTROPLATING METHOD

PETITION FOR EXTENSION OF TIME

Mail Stop Extension of Time Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

It is respectfully requested that the time for response to the Office Action dated December 11, 2003, now due to expire March 11, 2003, be extended for two month(s) and set to expire on June 11, 2003. Please charge the extension fee of \$930.00 to Deposit Account No. 500417. Please charge any additional fees or credit any overpayment to Deposit Account No. 500417.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

Daniel Bucca, Ph.D.

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